



LT8643 4mmX4mmX0.94mm (TABLE OF MATERIAL DECLARATION)

This product is RoHS compliant per EU RoHS Directive 2015/863/EU.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	HL832NSF-LCA, AUS308	0.0077	Cured thermosetting resin (including inorganic filler)	Trade secret	0.00154	20.04
				Continuous Filament Fiber Glass	65997-17-3	0.00109	14.23
				Copper	7440-50-8	0.00379	49.37
				Modified Epoxy Acrylate Resin	186511-06-8	0.00044	5.67
				C.I pigment blue 15	147-14-8	0.00000	0.06
				Silicon dioxide	7631-86-9	0.00023	2.94
				Barium Sulfate	7727-43-7	0.00000	0.02
				3-methoxy-3-methylbutylacetate	103429-90-9	0.00007	0.93
				Organic yellow pigment	Trade secret	0.00000	0.06
				Dipropylene glycol monomethyl ether	34590-94-8	0.00004	0.51
				Heavy Aromatic Solvent naphtha	64742-94-5	0.00013	1.71
				Talc	14807-96-6	0.00019	2.44
				Gold	7440-57-5	0.00002	0.28
Nickel	7440-02-0	0.00013	1.74				
2	Die	Silicon	0.0021	Silicon	7440-21-3	0.00210	100.00
3	Component	Passive	0.0039	Copper (Cu)	7440-50-8	0.00125	32.00
				Nickel (Ni)	7440-02-0	0.00031	8.00
				Tin (Sn)	7440-31-5	0.00009	2.40
				Ceramic (Ba) Compounds	12047-27-7	0.00225	57.60
4	Solder paste	95Sn5Sb	0.0006	Tin (Sn)	7440-31-5	0.00060	95.00
				Antimony (Sb)	7440-36-0	0.00003	5.00
5	Flipchip Bump	Copper Pillar	0.0004	Copper (Cu)	7440-50-8	0.00026	61.87
				Tin (Sn)	7440-31-5	0.00015	37.36
				Silver (Ag)	7440-22-4	0.00000	0.76
6	Encapsulation	EpoxyResin	0.0238	Solid Epoxy Resin	Trade secret	0.00071	3.00
				Phenol Resin	Trade secret	0.00071	3.00
				Fused Silica	60676-86-0	0.02155	90.50
				Carbon Black	1333-86-4	0.00012	0.50
				Metal Hydroxide	Trade secret	0.00071	3.00
Total Package Weight			0.0385				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts